

# MOSFET – Power, Single N-Channel, DFNW8

80 V, 229 A, 2 mΩ

## NTMTS002N08MC

### Features

- Small Footprint (8x8 mm) for Compact Design
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low  $Q_G$  and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Typical Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-to-Source Voltage	80	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current $R_{\theta JC}$ (Note 2)	229	A
$P_D$	Power Dissipation $R_{\theta JC}$ (Note 2)		
$I_D$	Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	29	A
$P_D$	Power Dissipation $R_{\theta JA}$ (Notes 1, 2)		
$I_{DM}$	Pulsed Drain Current	3577	A
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$E_{AS}$	Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 29\text{ A}$ , $L = 3\text{ mH}$ )	1261.5	mJ
$T_L$	Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	260	$^\circ\text{C}$

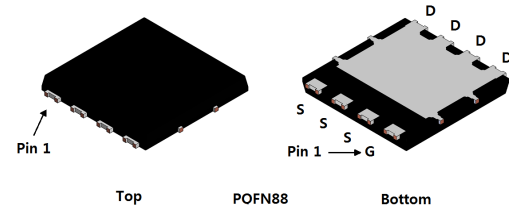
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL RESISTANCE MAXIMUM RATINGS

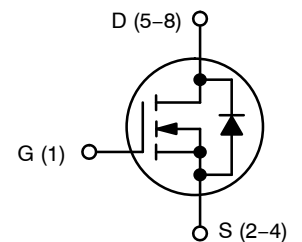
Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Junction-to-Case – Steady State (Note 2)	0.6	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient – Steady State (Note 2)	38	

1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 1 oz. Cu pad.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
80 V	2 mΩ @ 10 V	229 A
	5.1 mΩ @ 6 V	

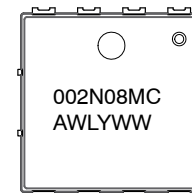


DFNW8  
CASE 507AP



N-CHANNEL MOSFET

### MARKING DIAGRAM



002N08MC = Device Code  
A = Assembly Location  
WL = 2-digit Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# NTMTS002N08MC

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	80			V
$V_{(BR)DSS}/T_J$	Drain-to-Source Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$		68		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{ V}, V_{DS} = 80\text{ V}$	$T_J = 25^\circ\text{C}$		1	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$		250	
$I_{GSS}$	Gate-to-Source Leakage Current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA

### ON CHARACTERISTICS (Note 3)

$V_{GS(TH)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 540\text{ }\mu\text{A}$	2.0	2.7	4.0	V
$V_{GS(TH)}/T_J$	Negative Threshold Temperature Coefficient	$I_D = 540\text{ }\mu\text{A}$ , ref to $25^\circ\text{C}$		-7.9		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 90\text{ A}$		1.3	2.0	m $\Omega$
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 6\text{ V}, I_D = 48\text{ A}$		1.8	5.1	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 90\text{ A}$		214		S
$R_G$	Gate Resistance	$T_A = 25^\circ\text{C}$		0.8		$\Omega$

### CHARGES, CAPACITANCES & GATE RESISTANCE

$C_{ISS}$	Input Capacitance	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 40\text{ V}$		6350	8900	pF
$C_{OSS}$	Output Capacitance			2100	3000	
$C_{RSS}$	Reverse Transfer Capacitance			93	130	
$Q_{G(TOT)}$	Total Gate Charge	$V_{GS} = 10\text{ V}, V_{DS} = 40\text{ V}; I_D = 90\text{ A}$		89	125	nC
$Q_{G(TH)}$	Threshold Gate Charge			16	22	
$Q_{GS}$	Gate-to-Source Charge			25		
$Q_{GD}$	Gate-to-Drain Charge			19		
$Q_{OSS}$	Output Charge			117		
$Q_{sync}$	Sync Charge			72		
$V_{plateau}$	Plateau Voltage			4		V

### SWITCHING CHARACTERISTICS, $V_{GS} = 10\text{ V}$ (Note 3)

$t_{d(ON)}$	Turn-On Delay Time	$V_{GS} = 10\text{ V}, V_{DS} = 40\text{ V}, I_D = 90\text{ A}, R_G = 6\text{ }\Omega$		26		ns
$t_r$	Rise Time			20		
$t_{d(OFF)}$	Turn-Off Delay Time			65		
$t_f$	Fall Time			29		

### DRAIN-SOURCE DIODE CHARACTERISTICS

$V_{SD}$	Forward Diode Voltage	$V_{GS} = 0\text{ V}, I_S = 2\text{ A}$		0.7	1.2	V
		$V_{GS} = 0\text{ V}, I_S = 90\text{ A}$		0.8	1.3	
$t_{RR}$	Reverse Recovery Time	$I_F = 45\text{ A}, di/dt = 300\text{ A}/\mu\text{s}$		34	54	ns
$Q_{RR}$	Reverse Recovery Charge			71	114	
$t_{RR}$	Reverse Recovery Time	$I_F = 45\text{ A}, di/dt = 1000\text{ A}/\mu\text{s}$		27	43	nC
$Q_{RR}$	Reverse Recovery Charge			177	283	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

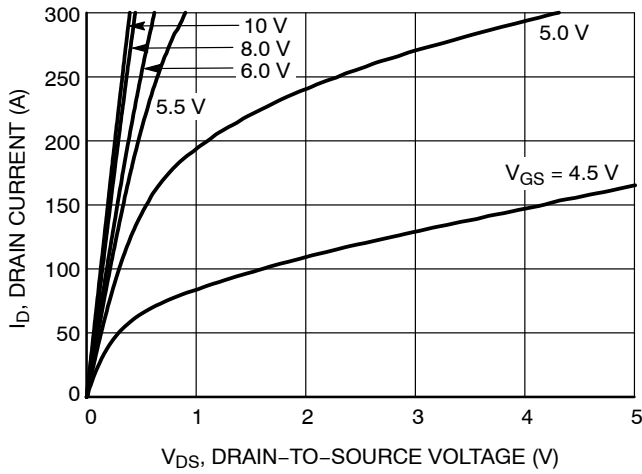


Figure 1. On-Region Characteristics

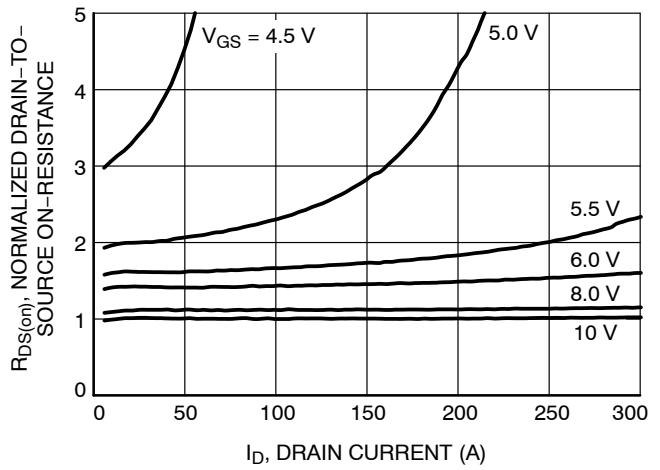


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

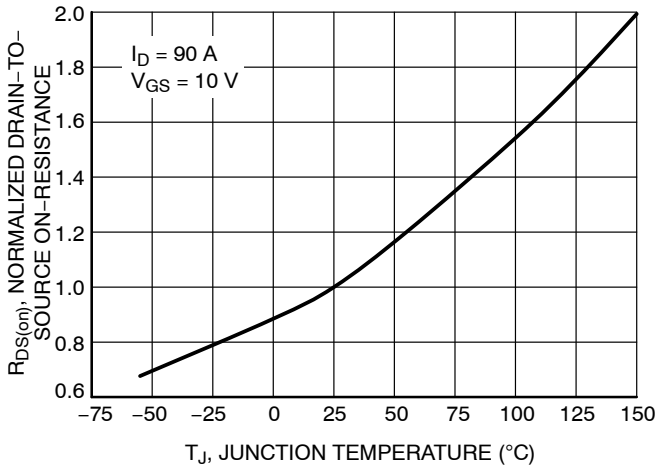


Figure 3. Normalized On Resistance vs. Junction Temperature

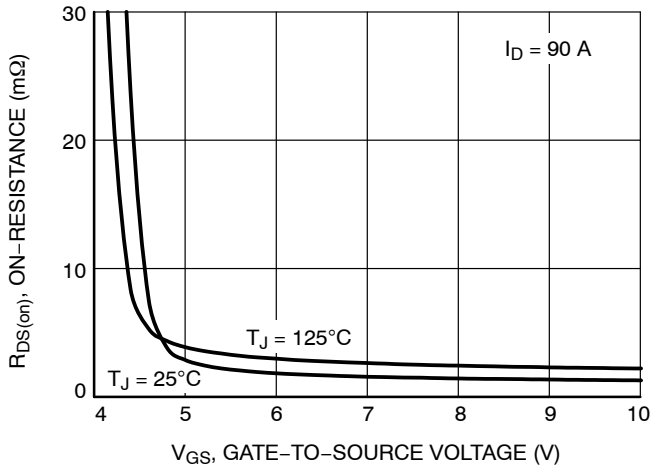


Figure 4. On-Resistance vs. Gate-to-Source Voltage

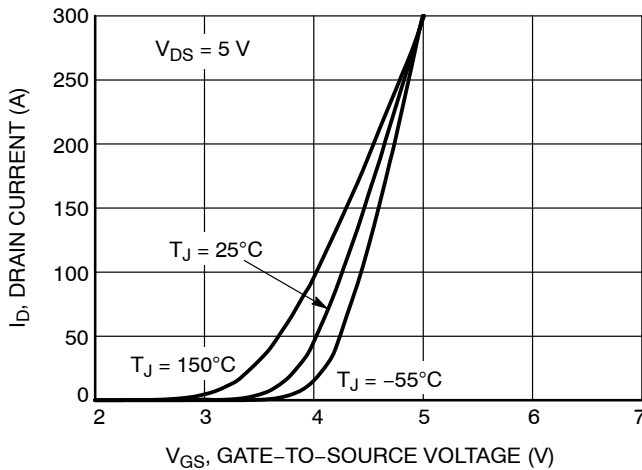


Figure 5. Transfer Characteristics

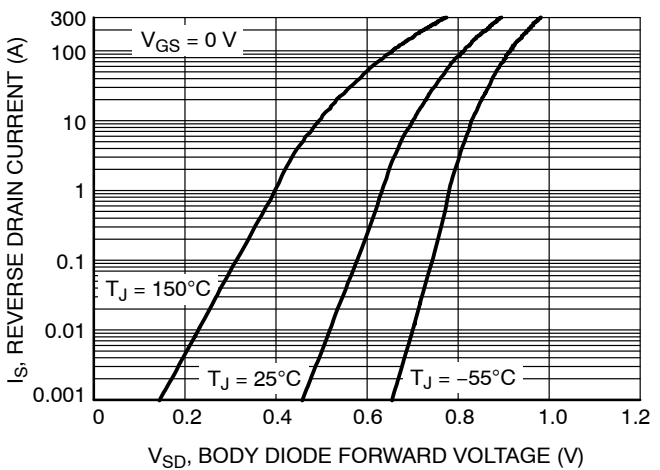


Figure 6. Source-to-Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS (continued)

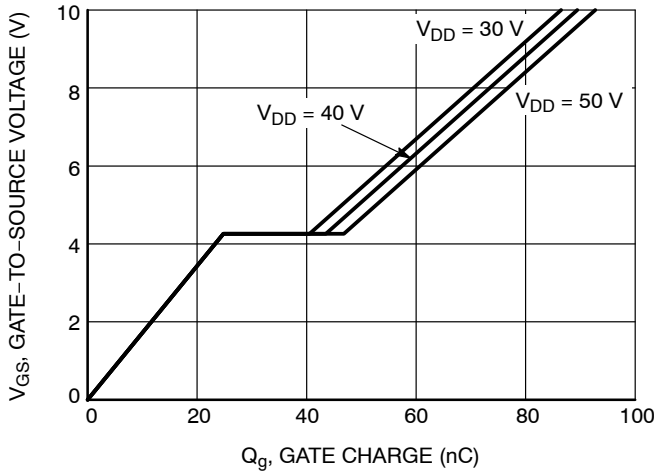


Figure 7. Gate Charge Characteristics

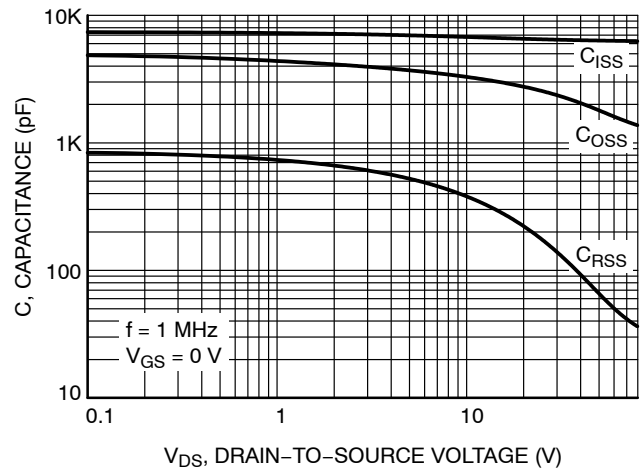


Figure 8. Capacitance vs. Drain-to-Source Voltage

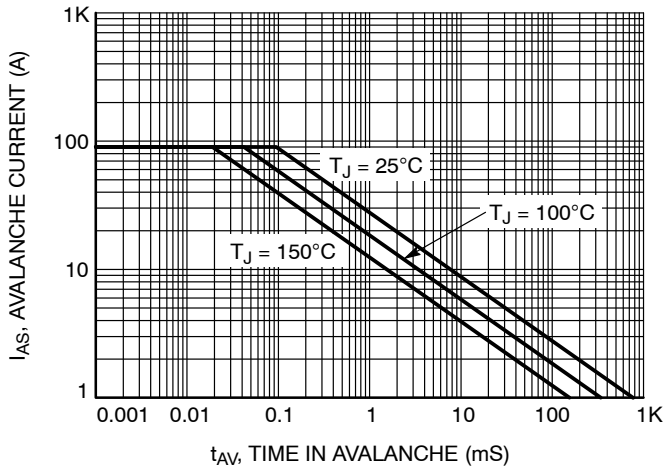


Figure 9. Unclamped Inductive Switching Capability

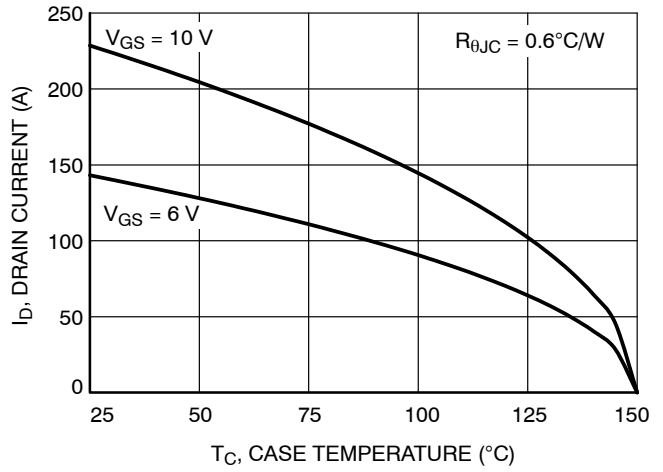


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

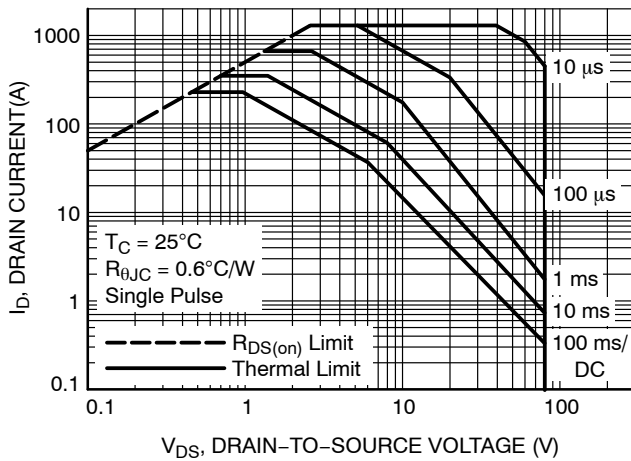


Figure 11. Forward Biased Safe Operating Area

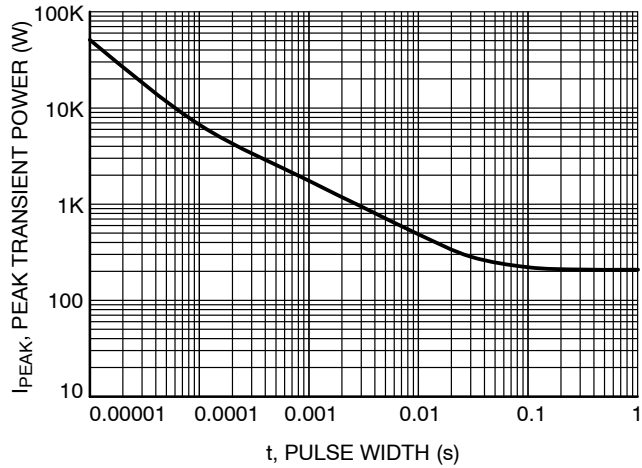


Figure 12. Single Pulse Maximum Power Dissipation

# NTMTS002N08MC

## TYPICAL CHARACTERISTICS (continued)

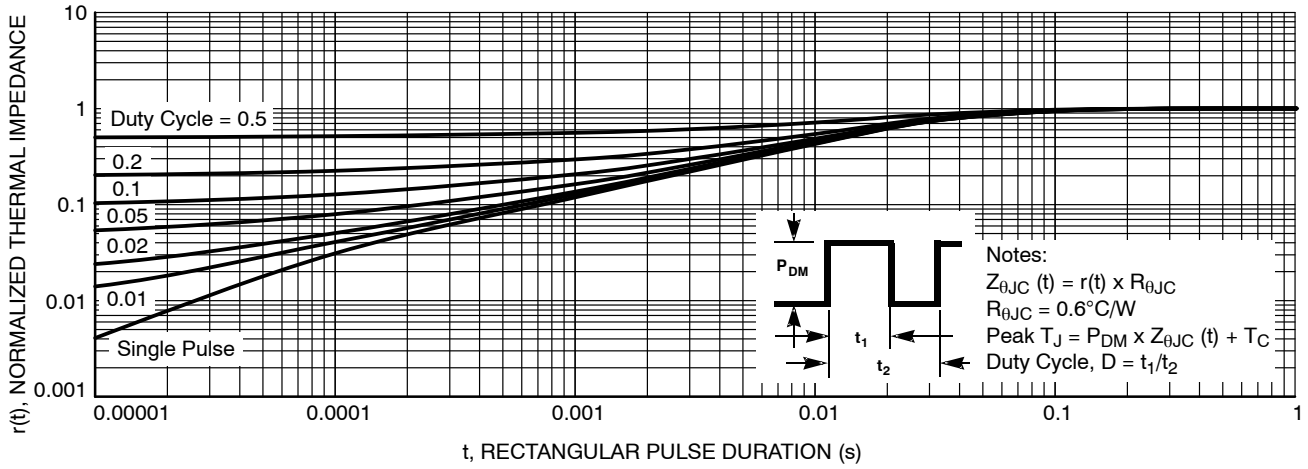


Figure 13. Transient Thermal Impedance

### DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping <sup>†</sup>
NTMTS002N08MC	NTMTS 002N08MC	DFNW8 (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).


**TDFNW8 8.30x8.40x1.10, 2.00P**  
**CASE 507AP**  
**ISSUE E**

DATE 08 MAY 2024



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.00	1.10	1.20
A1	0.00	—	0.05
b	0.90	1.00	1.10
b1	0.35	0.45	0.55
c	0.23	0.28	0.33
D	8.20	8.30	8.40
D1	7.90	8.00	8.10
D2	6.80	6.90	7.00
D3	6.90	7.00	7.10
E	8.30	8.40	8.50
E1	7.80	7.90	8.00
E2	5.24	5.34	5.44
E3	0.25	0.35	0.45
e	2.00 BSC		
e/2	1.00 BSC		
e1	2.70 BSC		
e1/2	1.35 BSC		
K	1.50	1.57	1.70
L	0.64	0.74	0.84
L1	0.67	0.77	0.87
Θ	0°	—	12°

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**TDFNW8 8.30x8.40x1.10, 2.00P**  
**CASE 507AP**  
**ISSUE E**

DATE 08 MAY 2024

**GENERIC  
MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot Code  
Y = Year Code  
WW = Work Week Code

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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